



# MicroSIZE, Single-Supply CMOS OPERATIONAL AMPLIFIERS

## MicroAmplifier™ Series

### FEATURES

- **MicroSIZE PACKAGES:**  
SOT23-5, SOT23-8
- **SINGLE-SUPPLY OPERATION**
- **RAIL-TO-RAIL OUTPUT SWING**
- **FET-INPUT:  $I_B = 10\text{pA max}$**
- **HIGH SPEED:**  
OPA337: 3MHz, 1.2V/ $\mu\text{s}$  ( $G = 1$ )  
OPA338: 12.5MHz, 4.6V/ $\mu\text{s}$  ( $G = 5$ )
- **OPERATION FROM 2.5V to 5.5V**
- **HIGH OPEN-LOOP GAIN: 120dB**
- **LOW QUIESCENT CURRENT: 525 $\mu\text{A/amp}$**
- **SINGLE AND DUAL VERSIONS**

### APPLICATIONS

- **BATTERY-POWERED INSTRUMENTS**
- **PHOTODIODE PRE-AMPS**
- **MEDICAL INSTRUMENTS**
- **TEST EQUIPMENT**
- **AUDIO SYSTEMS**
- **DRIVING ADCs**
- **CONSUMER PRODUCTS**

SPIICE model available at [www.ti.com](http://www.ti.com).

### DESCRIPTION

The OPA337 and OPA338 series rail-to-rail output CMOS operational amplifiers are designed for low cost and miniature applications. Packaged in the SOT23-8, the OPA2337EA and OPA2338EA are Texas Instruments' smallest dual op amps. At 1/4 the size of a conventional SO-8 surface-mount, they are ideal for space-sensitive applications.

Utilizing advanced CMOS technology, the OPA337 and OPA338 op amps provide low bias current, high-speed operation, high open-loop gain, and rail-to-rail output swing. They operate on a single supply with operation as low as 2.5V while drawing only 525 $\mu\text{A}$  quiescent current. In addition, the input common-mode voltage range includes ground—ideal for single-supply operation.

The OPA337 series is unity-gain stable. The OPA338 series is optimized for gains greater than or equal to 5. They are easy-to-use and free from phase inversion and overload problems found in some other op amps. Excellent performance is maintained as the amplifiers swing to their specified limits. The dual versions feature completely independent circuitry for lowest crosstalk and freedom from interaction, even when overdriven or overloaded.

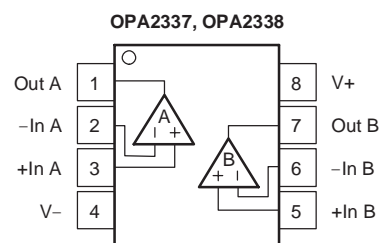
PACKAGE	G = 1 STABLE		G ≥ 5 STABLE	
	SINGLE OPA337	DUAL OPA2337	SINGLE OPA338	DUAL OPA2338
SOT23-5	✓		✓	
SOT23-8		✓		✓
MSOP-8	✓			
SO-8	✓	✓	✓	✓
DIP-8	✓	✓		



DIP-8<sup>(1)</sup>, SO-8, MSOP-8<sup>(1)</sup>  
NC = No Connection



NOTE: (1) DIP AND MSOP-8 versions for OPA337, OPA2337 only.



DIP-8<sup>(1)</sup>, SO-8, SOT23-8



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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**ABSOLUTE MAXIMUM RATINGS(1)**

Supply Voltage .....	7.5V
Input Voltage(2) .....	(V-) – 0.5V to (V+) + 0.5V
Input Current(2) .....	10mA
Output Short Circuit(3) .....	Continuous
Operating Temperature .....	–55°C to +125°C
Storage Temperature .....	–55°C to +125°C
Junction Temperature .....	150°C
Lead Temperature (soldering, 10s) .....	300°C

- (1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not supported.
- (2) Input signal voltage is limited by internal diodes connected to power supplies. See text.
- (3) Short-circuit to ground, one amplifier per package.



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

**ORDERING INFORMATION(1)**

PRODUCT	DESCRIPTION	PACKAGE-LEAD	PACKAGE DESIGNATOR	SPECIFIED TEMPERATURE RANGE	PACKAGE MARKING	ORDERING NUMBER	TRANSPORT MEDIA, QUANTITY
OPA337 Series	Single, G = 1 Stable	SOT23-5	DBV	–40°C to +85°C	C37	OPA337NA/250	Tape and Reel, 250
		MSOP-8	DGK		G37	OPA337NA/3K	Tape and Reel, 3000
		DIP-8	P		OPA337PA	OPA337EA/250	Tape and Reel, 250
		SO-8 Surface-Mount	D		OPA337UA	OPA337EA/2K5	Tape and Reel, 2500
OPA2337	Dual, G = 1 Stable	SOT23-8	DCN	–40°C to +85°C	A7	OPA2337EA/250	Tape and Reel, 250
		DIP-8	P		OPA2337PA	OPA2337EA/3K	Tape and Reel, 3000
		SO-8	D		OPA2337UA	OPA2337PA	Rails
		Surface-Mount			OPA2337UA	OPA2337UA	Rails
OPA338 Series	Single, G ≥ 5 Stable	SOT23-5	DBV	–40°C to +85°C	A38	OPA338NA/250	Tape and Reel, 250
		SO-8	D		OPA338UA	OPA338NA/3K	Tape and Reel, 3000
		Surface-Mount			OPA338UA	OPA338UA	Rails
					OPA338UA/2K5	OPA338UA/2K5	Tape and Reel, 2500
OPA2338	Dual, G ≥ 5 Stable	SOT23-8	DCN	–40°C to +85°C	A8	OPA2338EA/250	Tape and Reel, 250
		SO-8	D		OPA2338UA	OPA2338EA/3K	Tape and Reel, 3000
		Surface-Mount			OPA2338UA	OPA2338UA	Rails
					OPA2338UA/2K5	OPA2338UA/2K5	Tape and Reel, 2500

(1) For the most current package and ordering information, see the Package Option Addendum located at the end of this data sheet.

**ELECTRICAL CHARACTERISTICS:  $V_S = 2.7V$  to  $5.5V$**

**Boldface** limits apply over the specified temperature range,  $-40^{\circ}C$  to  $+85^{\circ}C$ ,  $V_S = 5V$ .

At  $T_A = +25^{\circ}C$  and  $R_L = 25k\Omega$  connected to  $V_S/2$ , unless otherwise noted.

PARAMETER	CONDITION	OPA337, OPA2337, OPA338, OPA2338			UNIT	
		MIN	TYP(1)	MAX		
<b>OFFSET VOLTAGE</b>						
Input Offset Voltage $T_A = -40^{\circ}C$ to $+85^{\circ}C$	$V_{OS}$		$\pm 0.5$	$\pm 3$	mV	
vs Temperature	$dV_{OS}/dT$		$\pm 2$	<b><math>\pm 3.5</math></b>	mV	
vs Power-Supply Rejection Ratio $T_A = -40^{\circ}C$ to $+85^{\circ}C$	PSRR		25	125	$\mu V/^{\circ}C$	
Channel Separation (dual versions)	dc		0.3	<b>125</b>	$\mu V/V$	
<b>INPUT BIAS CURRENT</b>						
Input Bias Current $T_A = -40^{\circ}C$ to $+85^{\circ}C$	$I_B$		$\pm 0.2$	$\pm 10$	pA	
Input Offset Current	$I_{OS}$		See Typical Curve		pA	
<b>NOISE</b>						
Input Voltage Noise, $f = 0.1Hz$ to $10Hz$			6		$\mu V_{PP}$	
Input Voltage Noise Density, $f = 1kHz$	$e_n$		26		$nV/\sqrt{Hz}$	
Current Noise Density, $f = 1kHz$	$i_n$		0.6		$fA/\sqrt{Hz}$	
<b>INPUT VOLTAGE RANGE</b>						
Common-Mode Voltage Range	$V_{CM}$	$T_A = -40^{\circ}C$ to $+85^{\circ}C$	<b>-0.2</b>		$(V+) - 1.2$	V
Common-Mode Rejection Ratio	CMRR	$-0.2V < V_{CM} < (V+) - 1.2V$	74	90		dB
		$-0.2V < V_{CM} < (V+) - 1.2V$	<b>74</b>			dB
<b>INPUT IMPEDANCE</b>						
Differential				$10^{13}    2$	$\Omega    pF$	
Common-Mode				$10^{13}    4$	$\Omega    pF$	
<b>OPEN-LOOP GAIN</b>						
Open-Loop Voltage Gain $T_A = -40^{\circ}C$ to $+85^{\circ}C$	$A_{OL}$	$R_L = 25k\Omega, 125mV < V_O < (V+) - 125mV$	100	120	dB	
		<b><math>R_L = 25k\Omega, 125mV &lt; V_O &lt; (V+) - 125mV</math></b>	<b>100</b>		dB	
		$R_L = 5k\Omega, 500mV < V_O < (V+) - 500mV$	100	114	dB	
		<b><math>R_L = 5k\Omega, 500mV &lt; V_O &lt; (V+) - 500mV</math></b>	<b>100</b>		dB	
<b>OPA337 FREQUENCY RESPONSE</b>						
Gain-Bandwidth Product	GBW	$V_S = 5V, G = 1$		3	MHz	
Slew Rate	SR	$V_S = 5V, G = 1$		1.2	$V/\mu s$	
Settling Time: 0.1%		$V_S = 5V, 2V$ Step, $C_L = 100pF, G = 1$		2	$\mu s$	
0.01%		$V_S = 5V, 2V$ Step, $C_L = 100pF, G = 1$		2.5	$\mu s$	
Overload Recovery Time		$V_{IN} \times G = V_S$		2	$\mu s$	
Total Harmonic Distortion + Noise	THD+N	$V_S = 5V, V_O = 3V_{PP}, G = 1, f = 1kHz$		0.001	%	
<b>OPA338 FREQUENCY RESPONSE</b>						
Gain-Bandwidth Product	GBW	$V_S = 5V, G = 5$		12.5	MHz	
Slew Rate	SR	$V_S = 5V, G = 5$		4.6	$V/\mu s$	
Settling Time: 0.1%		$V_S = 5V, 2V$ Step, $C_L = 100pF, G = 5$		1.4	$\mu s$	
0.01%		$V_S = 5V, 2V$ Step, $C_L = 100pF, G = 5$		1.9	$\mu s$	
Overload Recovery Time		$V_{IN} \times G = V_S$		0.5	$\mu s$	
Total Harmonic Distortion + Noise	THD+N	$V_S = 5V, V_O = 3V_{PP}, G = 5, f = 1kHz$		0.0035	%	

(1)  $V_S = 5V$ .

(2) Output voltage swings are measured between the output and negative and positive power-supply rails.

**ELECTRICAL CHARACTERISTICS:  $V_S = 2.7V$  to  $5.5V$  (continued)**

**Boldface** limits apply over the specified temperature range,  $-40^{\circ}C$  to  $+85^{\circ}C$ ,  $V_S = 5V$ .

At  $T_A = +25^{\circ}C$  and  $R_L = 25k\Omega$  connected to  $V_S/2$ , unless otherwise noted.

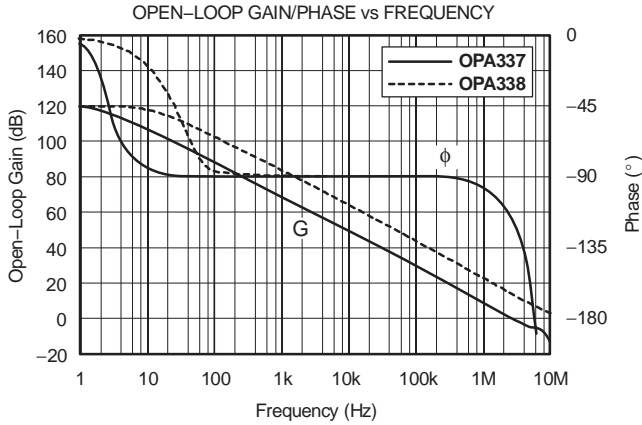
PARAMETER	CONDITION	OPA337, OPA2337, OPA338, OPA2338			UNIT
		MIN	TYP(1)	MAX	
<b>OUTPUT</b>					
Voltage Output Swing from Rail(2)	$R_L = 25k\Omega, A_{OL} \geq 100dB$		40	125	mV
$T_A = -40^{\circ}C$ to $+85^{\circ}C$	<b><math>R_L = 25k\Omega, A_{OL} \geq 100dB</math></b>			<b>125</b>	mV
	$R_L = 5k\Omega, A_{OL} \geq 100dB$		150	500	mV
$T_A = -40^{\circ}C$ to $+85^{\circ}C$	<b><math>R_L = 5k\Omega, A_{OL} \geq 100dB</math></b>			<b>500</b>	mV
Short-Circuit Current			$\pm 9$		mA
Capacitive Load Drive		See Typical Curve			
<b>POWER SUPPLY</b>					
Specified Voltage Range	$V_S$	<b>2.7</b>		<b>5.5</b>	V
Minimum Operating Voltage			2.5		V
Quiescent Current (per amplifier)	$I_Q$		0.525	1	mA
$T_A = -40^{\circ}C$ to $+85^{\circ}C$	$I_O = 0$ <b><math>I_O = 0</math></b>			<b>1.2</b>	mA
<b>TEMPERATURE RANGE</b>					
Specified Range		-40		+85	$^{\circ}C$
Operating Range		-55		+125	$^{\circ}C$
Storage Range		-55		+125	$^{\circ}C$
Thermal Resistance	$\theta_{JA}$				
SOT23-5 Surface-Mount			200		$^{\circ}C/W$
SOT23-8 Surface-Mount			200		$^{\circ}C/W$
MSOP-8			150		$^{\circ}C/W$
SO-8 Surface-Mount			150		$^{\circ}C/W$
DIP-8			100		$^{\circ}C/W$

(1)  $V_S = 5V$ .

(2) Output voltage swings are measured between the output and negative and positive power-supply rails.

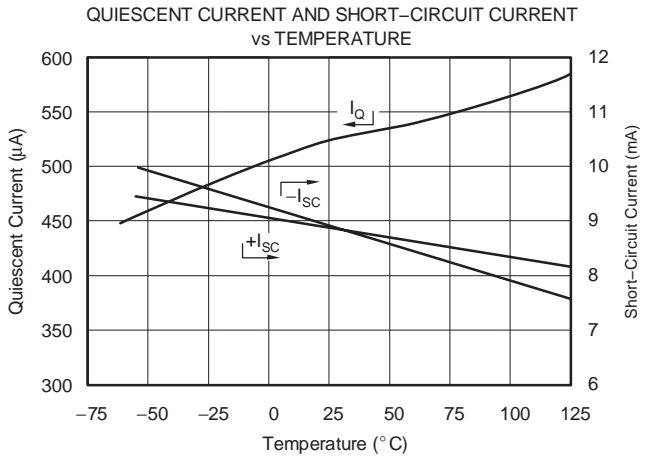
## TYPICAL CHARACTERISTICS

At  $T_A = +25^\circ\text{C}$ ,  $V_S = +5\text{V}$ , and  $R_L = 25\text{k}\Omega$  connected to  $V_S/2$ , unless otherwise noted.



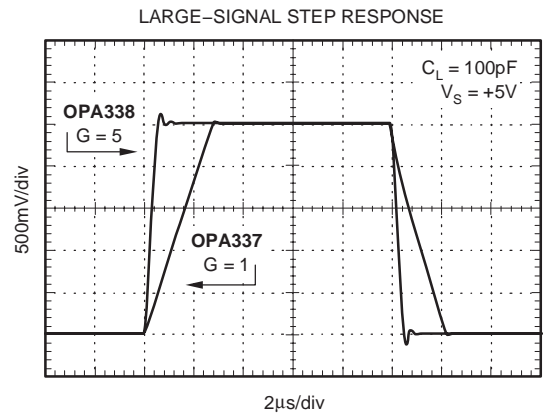
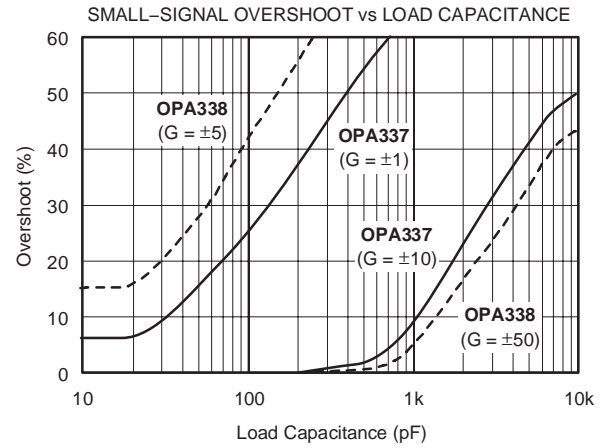
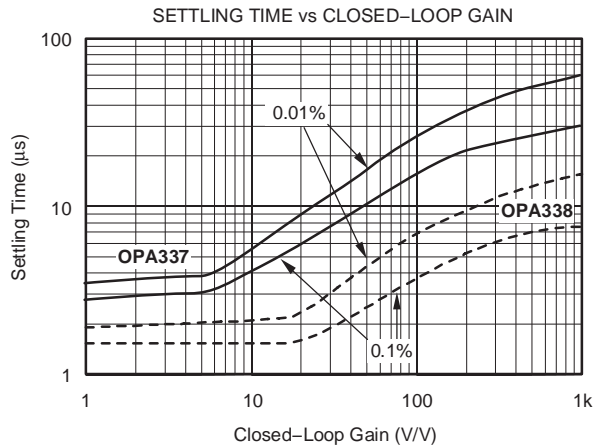
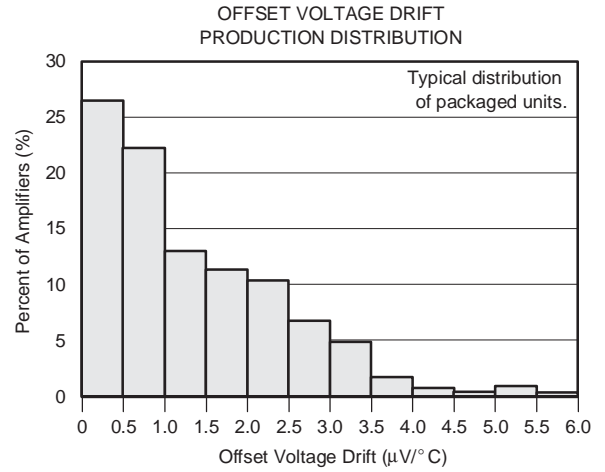
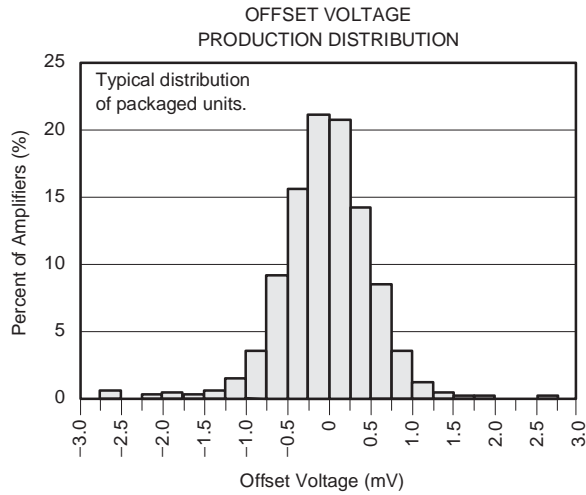
**TYPICAL CHARACTERISTICS (continued)**

At  $T_A = +25^\circ\text{C}$ ,  $V_S = +5\text{V}$ , and  $R_L = 25\text{k}\Omega$  connected to  $V_S/2$ , unless otherwise noted.



**TYPICAL CHARACTERISTICS (continued)**

At  $T_A = +25^\circ\text{C}$ ,  $V_S = +5\text{V}$ , and  $R_L = 25\text{k}\Omega$  connected to  $V_S/2$ , unless otherwise noted.



## APPLICATIONS INFORMATION

The OPA337 and OPA338 series are fabricated on a state-of-the-art CMOS process. The OPA337 series is unity-gain stable. The OPA338 series is optimized for gains greater than or equal to 5. Both are suitable for a wide range of general-purpose applications. Power-supply pins should be bypassed with 0.01μF ceramic capacitors.

### OPERATING VOLTAGE

The OPA337 series and OPA338 series can operate from a +2.5V to +5.5V single supply with excellent performance. Unlike most op amps which are specified at only one supply voltage, these op amps are specified for real-world applications; a single limit applies throughout the +2.7V to +5.5V supply range. This allows a designer to have the same assured performance at any supply voltage within the specified voltage range. Most behavior remains unchanged throughout the full operating voltage range. Parameters which vary significantly with operating voltage are shown in the Typical Characteristic curves.

### INPUT VOLTAGE

The input common-mode range extends from (V-) - 0.2V to (V+) - 1.2V. For normal operation, inputs should be limited to this range. The absolute maximum input voltage is 500mV beyond the supplies. Inputs greater than the input common-mode range but less than maximum input voltage, while not valid, will not cause any damage to the op amp. Furthermore, if input current is limited the inputs may go beyond the power supplies without phase inversion (as shown in Figure 1) unlike some other op amps.

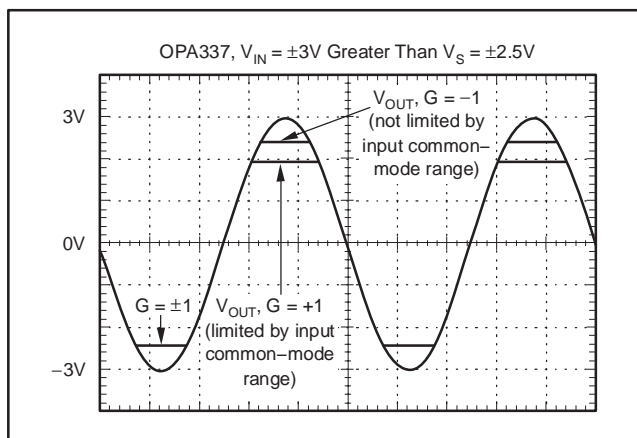


Figure 1. OPA337—No Phase Inversion with Inputs Greater than the Power-Supply Voltage

Normally, input currents are 0.2pA. However, large inputs (greater than 500mV beyond the supply rails) can cause excessive current to flow in or out of the input pins. Therefore, as well as keeping the input voltage below the maximum rating, it is also important to limit the input current to less than 10mA. This is easily accomplished with an input resistor as shown in Figure 2.

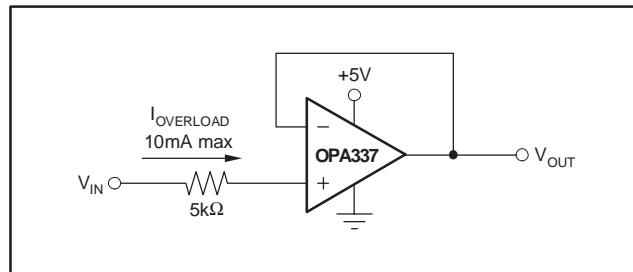


Figure 2. Input Current Protection for Voltages Exceeding the Supply Voltage

### USING THE OPA338 IN LOW GAINS

The OPA338 series is optimized for gains greater than or equal to 5. It has significantly wider bandwidth (12.5MHz) and faster slew rate (4.6V/μs) when compared to the OPA337 series. The OPA338 series can be used in lower gain configurations at low frequencies while maintaining its high slew rate with the proper compensation.

Figure 3 shows the OPA338 in a unity-gain buffer configuration. At dc, the compensation capacitor C<sub>1</sub> is effectively open resulting in 100% feedback (closed-loop gain = 1). As frequency increases, C<sub>1</sub> becomes lower impedance and closed-loop gain increases, eventually becoming 1 + R<sub>2</sub>/R<sub>1</sub> (in this case 5, which is equal to the minimum gain required for stability).

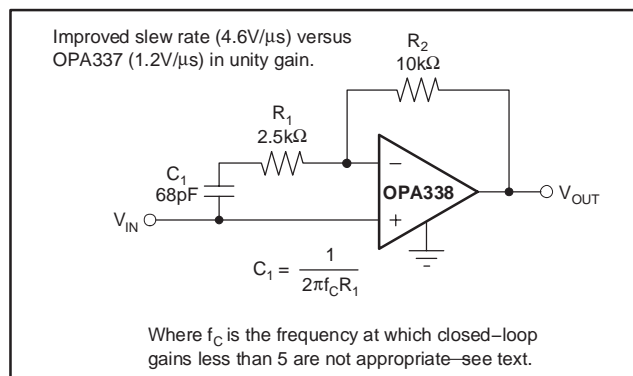


Figure 3. Compensation of the OPA338 for Unity-Gain Buffer



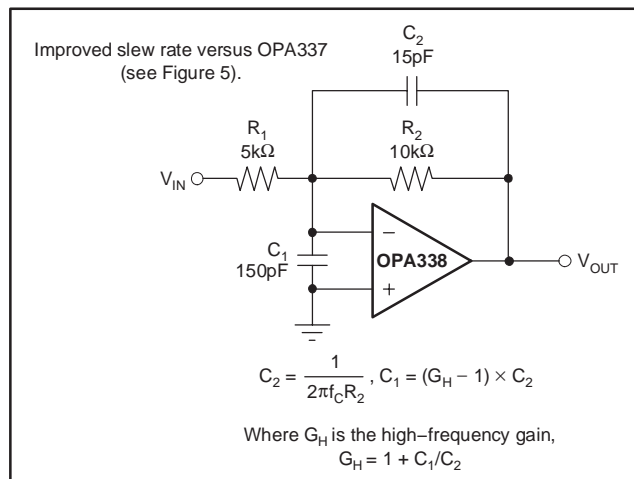
The required compensation capacitor value can be determined from the following equation:

$$C_1 = 1/(2\pi f_C R_1)$$

Since  $f_C$  may shift with process variations, it is recommended that a value less than  $f_C$  be used for determining  $C_1$ . With  $f_C = 1\text{MHz}$  and  $R_1 = 2.5\text{k}\Omega$ , the compensation capacitor is about 68pF.

The selection of the compensation capacitor  $C_1$  is important. A proper value ensures that the closed-loop circuit gain is greater than or equal to 5 at high frequencies. Referring to the *Open-Loop Gain vs Frequency* plot in the Typical Characteristics section, the OPA338 gain line (dashed in the curve) has a constant slope ( $-20\text{dB/decade}$ ) up to approximately 3MHz. This frequency is referred to as  $f_C$ . Beyond  $f_C$  the slope of the curve increases, suggesting that closed-loop gains less than 5 are not appropriate.

Figure 4 shows a compensation technique using an inverting configuration. The low-frequency gain is set by the resistor ratio while the high-frequency gain is set by the capacitor ratio. As with the noninverting circuit, for frequencies above  $f_C$  the gain must be greater than the recommended minimum stable gain for the op amp.



**Figure 4. Inverting Compensation Circuit of the OPA338 for Low Gain**

Resistors  $R_1$  and  $R_2$  are chosen to set the desired dc signal gain. Then the value for  $C_2$  is determined as follows:

$$C_2 = 1/(2\pi f_C R_2)$$

$C_1$  is determined from the desired high-frequency gain ( $G_H$ ):

$$C_1 = (G_H - 1) \times C_2$$

For a desired dc gain of 2 and high-frequency gain of 10, the following resistor and capacitor values result:

$$R_1 = 10\text{k}\Omega$$

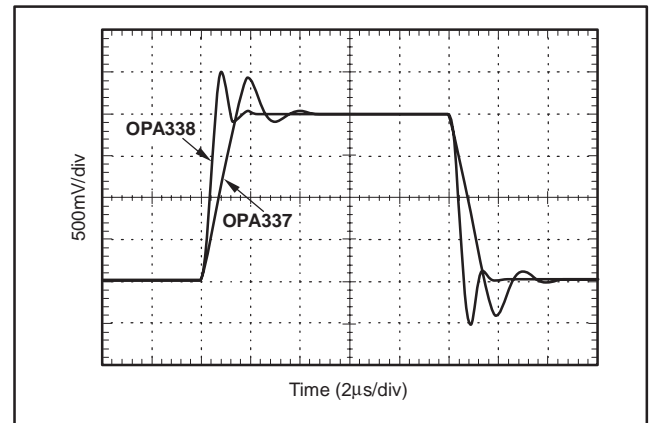
$$C_1 = 150\text{pF}$$

$$R_2 = 5\text{k}\Omega$$

$$C_2 = 15\text{pF}$$

The capacitor values shown are the nearest standard values. Capacitor values may need to be adjusted slightly to optimize performance. For more detailed information, consult the section on *Low Gain Compensation* in the OPA846 data sheet (SBOS250) located at [www.ti.com](http://www.ti.com).

Figure 5 shows the large-signal transient response using the circuit given in Figure 4. As shown, the OPA338 is stable in low gain applications and provides improved slew rate performance when compared to the OPA337.



**Figure 5.  $G = 2$ , Slew-Rate Comparison of the OPA338 and the OPA337**

## TYPICAL APPLICATION

See Figure 6 for the OPA2337 in a typical application. The ADS7822 is a 12-bit, micropower, sampling analog-to-digital converter available in the tiny MSOP-8 package. As with the OPA2337, it operates with a supply voltage as low as +2.7V. When used with the miniature SOT23-8 package of the OPA2337, the circuit is ideal for space-limited and low-power applications. In addition, the OPA2337's high input impedance allows large value resistors to be used which results in small physical capacitors, further reducing circuit size. For further information, consult the ADS7822 data sheet (SBAS062) located at [www.ti.com](http://www.ti.com).



Figure 6. Low-Power, Single-Supply, Speech Bandpass Filtered Data Acquisition System



Figure 7. Recommended SOT23-5 and SOT23-8 Solder Footprints

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/ Ball Finish	MSL Peak Temp <sup>(3)</sup>	Samples (Requires Login)
OPA2337EA/250	ACTIVE	SOT-23	DCN	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
OPA2337EA/250G4	ACTIVE	SOT-23	DCN	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
OPA2337EA/3K	ACTIVE	SOT-23	DCN	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
OPA2337EA/3KG4	ACTIVE	SOT-23	DCN	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
OPA2337PA	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	
OPA2337PAG4	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	
OPA2337UA	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
OPA2337UA/2K5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
OPA2337UA/2K5G4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
OPA2337UAG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
OPA2338EA/250	ACTIVE	SOT-23	DCN	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
OPA2338EA/250G4	ACTIVE	SOT-23	DCN	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
OPA2338EA/3K	ACTIVE	SOT-23	DCN	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
OPA2338EA/3KG4	ACTIVE	SOT-23	DCN	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
OPA2338UA	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
OPA2338UA/2K5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
OPA2338UA/2K5G4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/ Ball Finish	MSL Peak Temp <sup>(3)</sup>	Samples (Requires Login)
OPA2338UAG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
OPA337EA/250	ACTIVE	VSSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
OPA337EA/250G4	ACTIVE	VSSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
OPA337EA/2K5	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
OPA337EA/2K5G4	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
OPA337NA/250	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
OPA337NA/250G4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
OPA337NA/3K	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
OPA337NA/3KG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
OPA337PA	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	
OPA337PAG4	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	
OPA337UA	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
OPA337UA/2K5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
OPA337UA/2K5G4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
OPA337UAG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
OPA338NA/250	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
OPA338NA/250G4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
OPA338NA/3K	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/ Ball Finish	MSL Peak Temp <sup>(3)</sup>	Samples (Requires Login)
OPA338NA/3KG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
OPA338UA	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
OPA338UAG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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## TAPE AND REEL INFORMATION

### REEL DIMENSIONS



### TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

### TAPE AND REEL INFORMATION

\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
OPA2337EA/250	SOT-23	DCN	8	250	179.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
OPA2337EA/3K	SOT-23	DCN	8	3000	179.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
OPA2337UA/2K5	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
OPA2338EA/250	SOT-23	DCN	8	250	180.0	8.4	3.2	3.1	1.39	4.0	8.0	Q3
OPA2338EA/3K	SOT-23	DCN	8	3000	180.0	8.4	3.2	3.1	1.39	4.0	8.0	Q3
OPA2338UA/2K5	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
OPA337EA/250	VSSOP	DGK	8	250	180.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
OPA337EA/2K5	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
OPA337NA/250	SOT-23	DBV	5	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
OPA337NA/3K	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
OPA337NA/3K	SOT-23	DBV	5	3000	179.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
OPA337UA/2K5	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
OPA2337EA/250	SOT-23	DCN	8	250	195.0	200.0	45.0
OPA2337EA/3K	SOT-23	DCN	8	3000	195.0	200.0	45.0
OPA2337UA/2K5	SOIC	D	8	2500	367.0	367.0	35.0
OPA2338EA/250	SOT-23	DCN	8	250	210.0	185.0	35.0
OPA2338EA/3K	SOT-23	DCN	8	3000	210.0	185.0	35.0
OPA2338UA/2K5	SOIC	D	8	2500	367.0	367.0	35.0
OPA337EA/250	VSSOP	DGK	8	250	210.0	185.0	35.0
OPA337EA/2K5	VSSOP	DGK	8	2500	367.0	367.0	35.0
OPA337NA/250	SOT-23	DBV	5	250	180.0	180.0	18.0
OPA337NA/3K	SOT-23	DBV	5	3000	180.0	180.0	18.0
OPA337NA/3K	SOT-23	DBV	5	3000	203.0	203.0	35.0
OPA337UA/2K5	SOIC	D	8	2500	367.0	367.0	35.0

P (R-PDIP-T8)

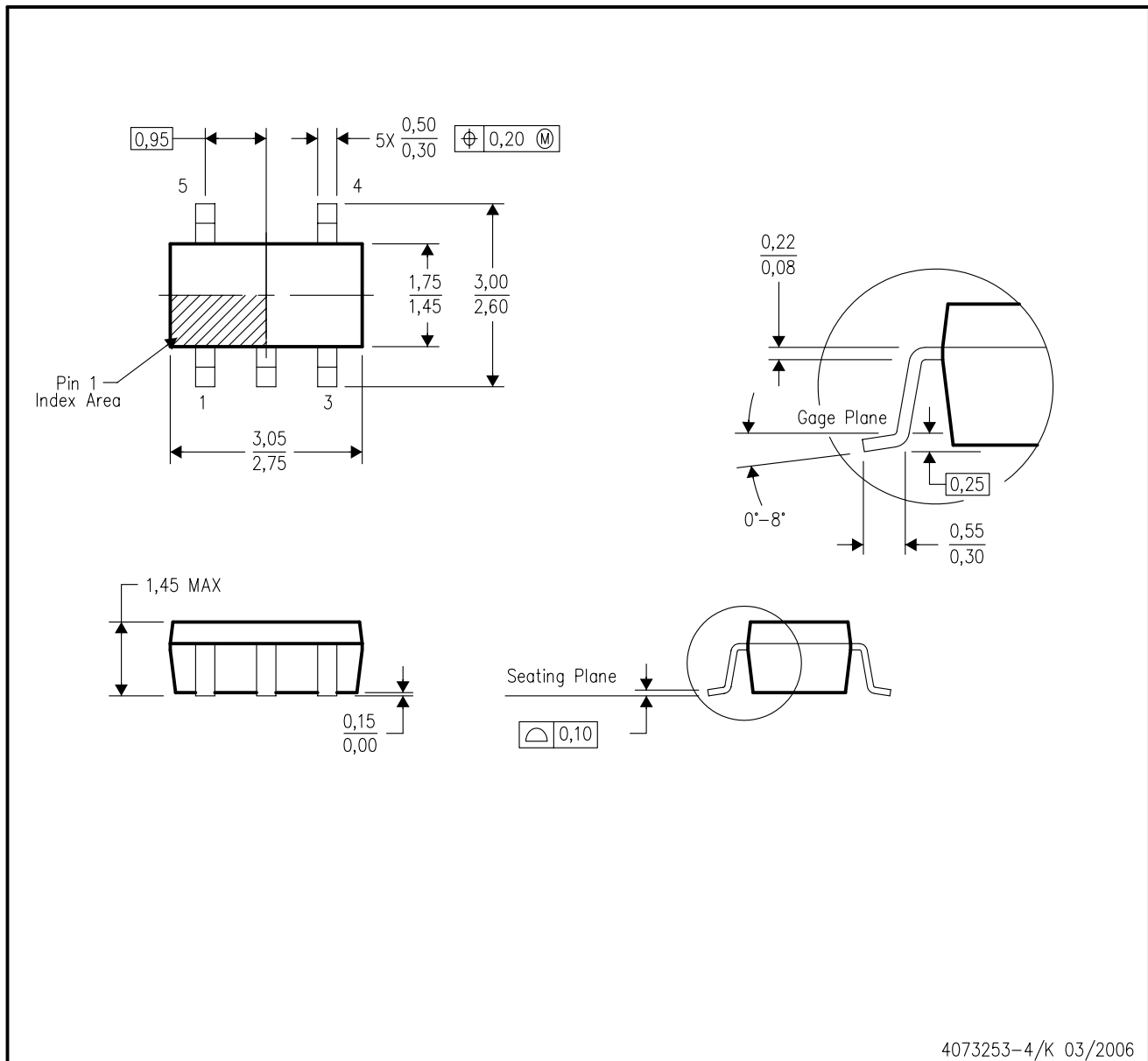
PLASTIC DUAL-IN-LINE PACKAGE





DBV (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
  - Falls within JEDEC MO-178 Variation AA.

DBV (R-PDSO-G5)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
  - D. Publication IPC-7351 is recommended for alternate designs.
  - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.

DGK (S-PDSO-G8)

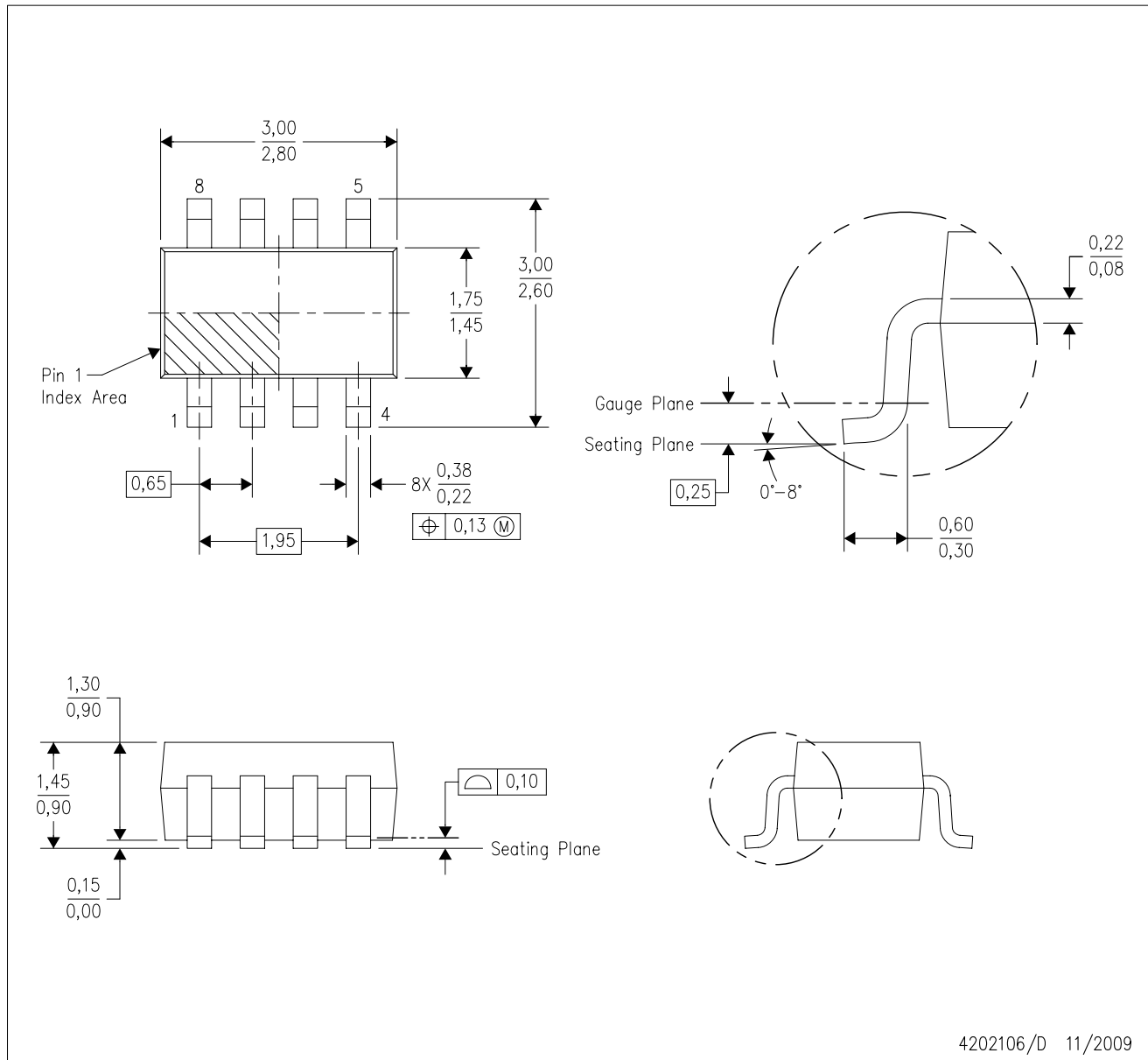
PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 per end.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed 0.50 per side.
  - E. Falls within JEDEC MO-187 variation AA, except interlead flash.

DCN (R-PDSO-G8)

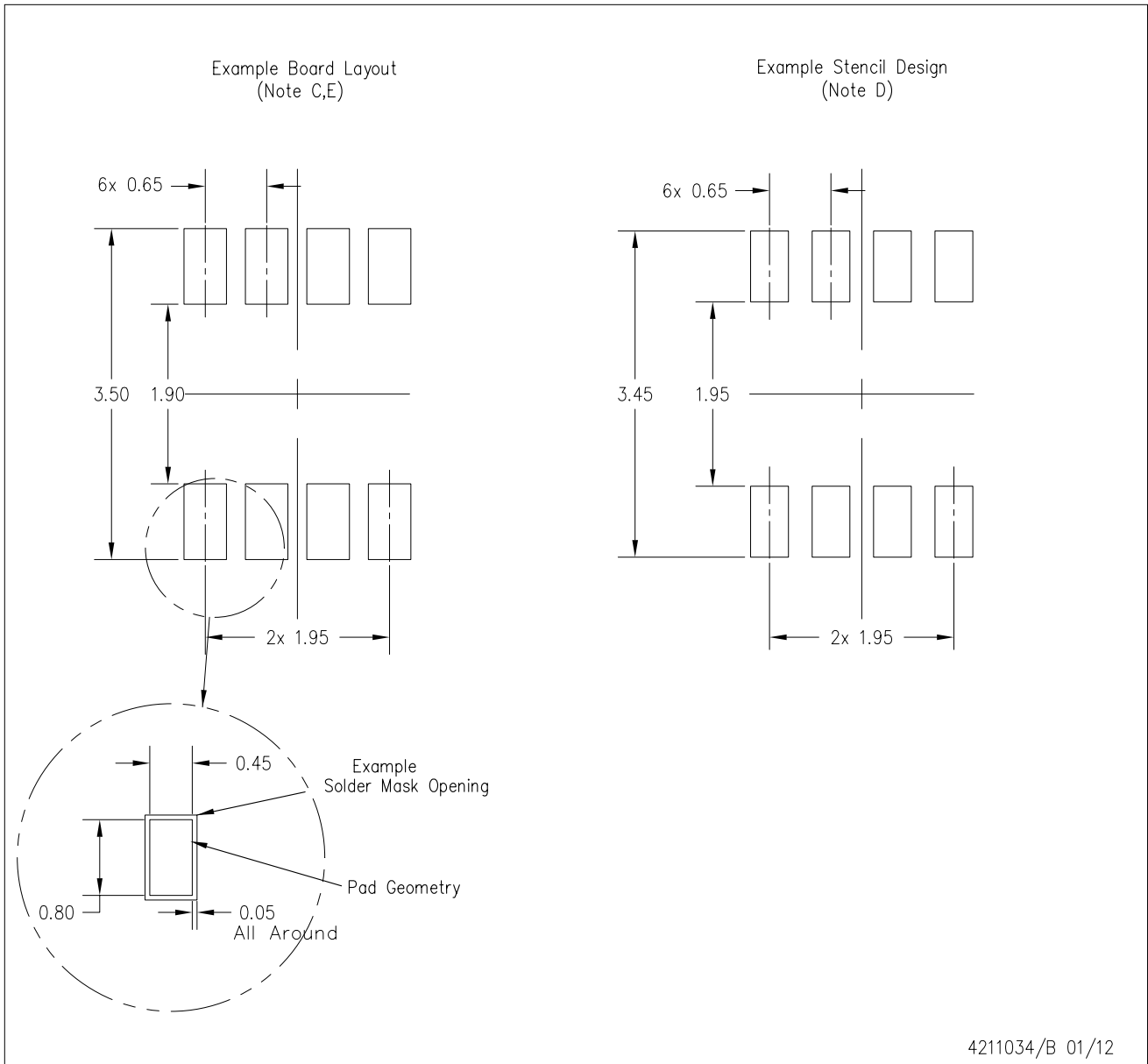
PLASTIC SMALL-OUTLINE PACKAGE (DIE DOWN)



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Package outline exclusive of metal burr & dambar protrusion/intrusion.
  - D. Package outline inclusive of solder plating.
  - E. A visual index feature must be located within the Pin 1 index area.
  - F. Falls within JEDEC MO-178 Variation BA.
  - G. Body dimensions do not include flash or protrusion. Mold flash and protrusion shall not exceed 0.25 per side.

DCN (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE (DIE DOWN)



4211034/B 01/12

- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate designs.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525.
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - $\triangle C$  Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
  - $\triangle D$  Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
  - E. Reference JEDEC MS-012 variation AA.

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



4211283-2/E 08/12

- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate designs.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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